

<b>PCN Number:</b>	20190424000.1		<b>PCN Date:</b>	Apr 24, 2019							
<b>Title:</b>	Qualify new Mount Compound Material for Select Package Device										
<b>Customer Contact:</b>	<a href="#">PCN Manager</a>	<b>Dept:</b>	Quality Services								
<b>Proposed 1<sup>st</sup> Ship Date:</b>	Jul. 24, 2019	<b>Estimated Sample Availability:</b>	Date provided at sample request								
<b>Change Type:</b>											
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site						
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material						
<input checked="" type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process						
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site						
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials						
				<input type="checkbox"/>	Wafer Fab Process						
<b>PCN Details</b>											
<b>Description of Change:</b>											
Texas Instruments is pleased to announce the qualification of new mount compound material for select package device. Devices will remain in current assembly facility and piece part changes as follows:											
<table border="1"> <thead> <tr> <th>Material</th> <th>From</th> <th>To</th> </tr> </thead> <tbody> <tr> <td>Mount compound</td> <td>1400348111</td> <td>1400329111</td> </tr> </tbody> </table>						Material	From	To	Mount compound	1400348111	1400329111
Material	From	To									
Mount compound	1400348111	1400329111									
<b>Reason for Change:</b>											
Continuity of supply.											
<b>Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):</b>											
None											
<b>Anticipated impact on Material Declaration</b>											
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the <a href="#">TI Eco-Info website</a> . There is no impact to the material meeting current regulatory compliance requirements with this PCN change.								
<b>Changes to product identification resulting from this PCN:</b>											
None											
<b>Product Affected:</b>											
SN74HC595BRWNR		SN74LVC244ARWPR									

# Qualification Report

Approve Date 26-Mar-2019

## Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: <u>SN74LVC244ARWPR</u>
TC	**T/C -65C/150C	-65C/+150C (500 Cycles)	1/77/0
MSL	Moisture Sensitivity (Cu Wire)	(per the appropriate pkg level)	1/12/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass
VM	Visual Quality Reliability Inspection	Post Temp Cycle	Pass
YLD	FTY and Bin Summary	-	Pass

- QBS: Qual By Similarity

- Qual Device SN74LVC244ARWPR is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

### Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

THIS INFORMATION RELATING TO QUALITY AND RELIABILITY IS PROVIDED "AS IS." Product information detailed in this report may not accurately reflect TI's current product materials, processes and testing used in the construction of the TI products. Customers are solely responsible to conduct sufficient engineering and additional qualification testing to determine whether a device is suitable for use in their applications. Using TI products outside limits stated in TI's datasheet may void TI's warranty. See TI's Terms of Sale at "<http://www.ti.com/lsds/ti/legal/termsofsale.page>"

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